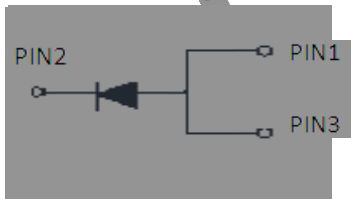
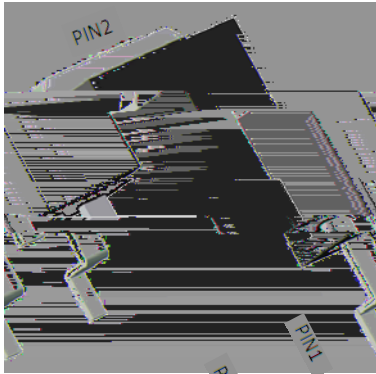


· · GW \ chh_m · · 8] cXYg ·



· : YUh i fYg ·

- High frequency operation
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- Guard ring for enhanced ruggedness and long term reliability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260

Hmd] WU · · 5 dd ·] WUh] cbg ·

Typical applications are in switching power supplies, converters, freewheeling diodes, and reverse battery protection.

A YW \ Ub] WU · · 8 UhU ·

DUW_U [Y: TO-263

Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant

HYf a] bU · g: Tin plated leads, solderable per J-STD-002 and JESD22-B102

Dc · Uf] hm: As marked

AUI] a i a · FUh] b] g (Ta=25 Unless otherwise specified

| | | | |
|--|-------|--------------------|----|
| | | | |
| | IRRM2 | VRM=VRRM Ta=100 | 50 |

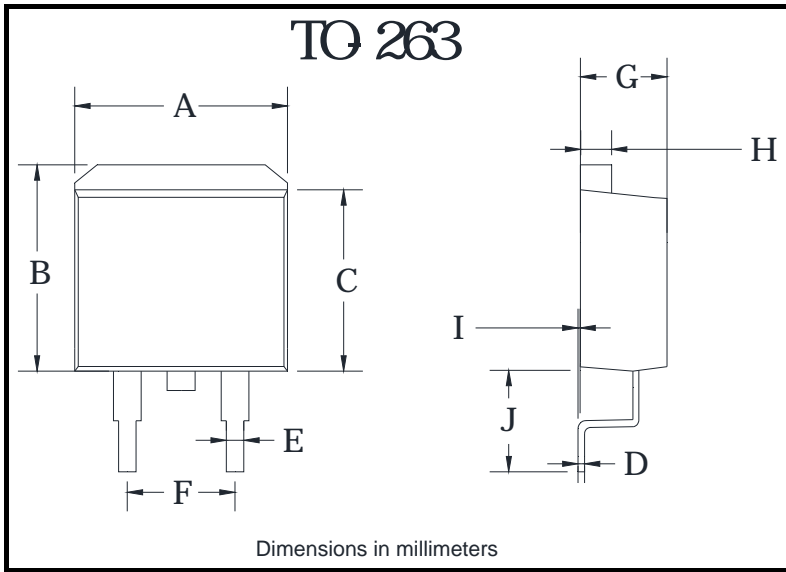


· ; : & \$ () A ; ·

H\Yf aU`7\UfUWhYf]gh]Wg` Ta



C i h`]bY`8]a Ybg]cbg`



| HC!&*` | | |
|--------|------|------|
| Dim | Min | Max |
| A | 9.5 | 11.5 |
| B | 9.7 | 10.5 |
| C | 8.4 | 9.0 |
| D | 0.28 | 0.64 |
| E | 0.68 | 0.94 |
| F | 4.55 | 5.6 |
| G | 4.04 | 5.10 |
| H | 1.14 | 1.4 |
| I | 0 | 0.2 |
| J | 4.9 | 6.05 |

